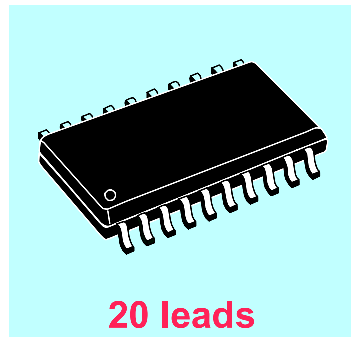
Thermal Data

SO 20



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.25 mm	2.61 W/cm°C
die attach	epoxy glue (silver filler)	10-40 µm	0.01 W/cm°C
molding compound	epoxy resin	2.45 mm	0.0063W/cm°C

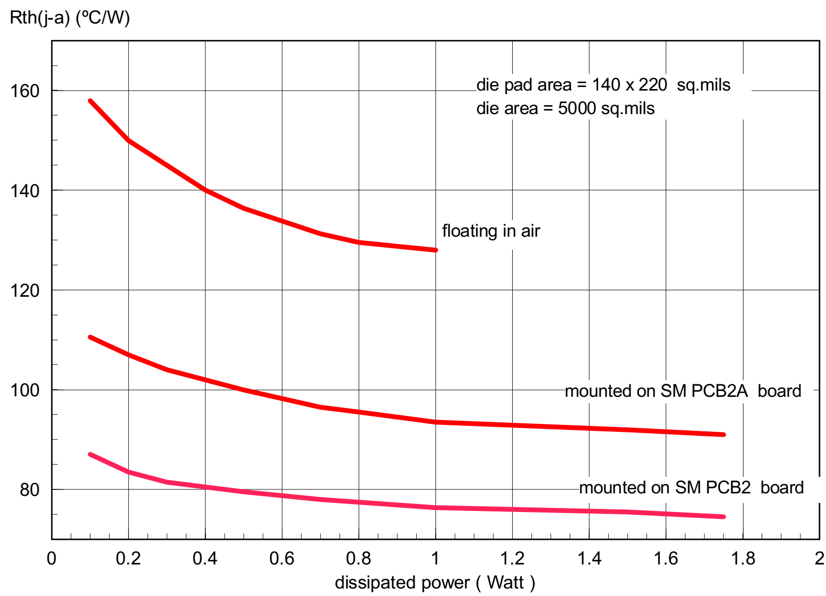
Charts enclosed :

1) Rth(j-a) vs power dissipation

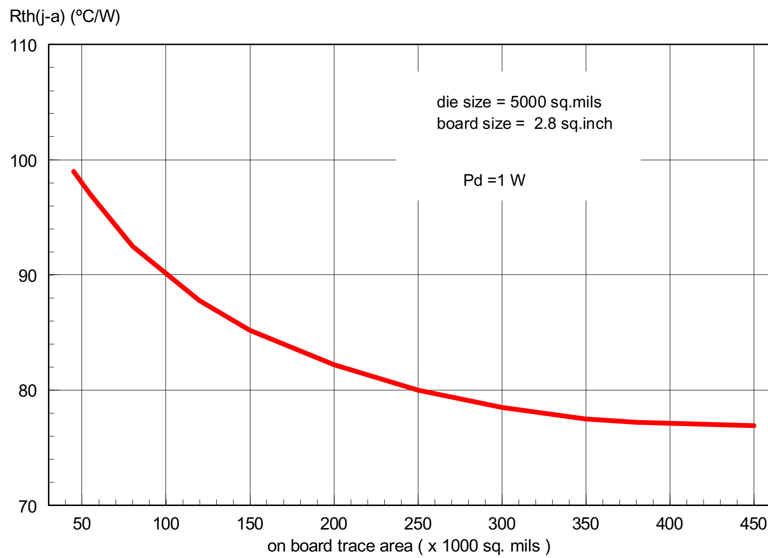
2) Rth(j-a) vs on board trace area

3) Zth(j-a) vs time width and die size

1)



2)



3)